



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD038N06N3 G	Issued	28. April 2021
MA#	MA000398200		
Package	PG-TO252-3-11	Weight*	373.88 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.184	1.39	1.39	13865	13865
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		576	
	non noble metal	copper	7440-50-8	215.017	57.49	57.57	575095	575844
wire	non noble metal	aluminium	7429-90-5	5.823	1.56	1.56	15574	15574
encapsulation	inorganic material	zinc oxide	1314-13-2	1.205	0.32		3224	
	miscellaneous	miscellaneous	-	6.026	1.61		16119	
	plastics	epoxy resin	-	18.079	4.84		48356	
	inorganic material	silicon dioxide	60676-86-0	95.218	25.47	32.24	254676	322375
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10003	10003
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.080	0.02		215	
	noble metal	silver	7440-22-4	0.100	0.03		268	
	non noble metal	lead	7439-92-1	3.833	1.03	1.08	10253	10736
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.13	5.14	51293	51359
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com